



深圳市一众显示科技有限公司

SHEN ZHEN TEAM SOURCE DISPLAY TECH. CO, LTD.

TFT-LCD Module Specification

Module NO.: TST057VGGH-02

Version: V1.0

APPROVAL FOR SPECIFICATION APPROVAL FOR SAMPLE

For Customer's Acceptance:	
Approved by	Comment

Team Source Display:		
Presented by	Reviewed by	Organized by

Records of Revision

DATE	REF.PAGE PARAGRAPH DRAWING No.	REVISED No.	SUMMARY	REMARK
2019-11-21		V1.0	First Issue	

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1. General Specification

Item	Contents	Unit
LCD TYPE	TFT/TRANSMISSIVE	
MODULE SIZE (W*H*T)	127.00*98.43*9.2(TOTAL)	MM
ACTIVE SIZE (W*H)	115.20*86.40	MM
PIXEL PITCH (W*H)	0.18*0.18	MM
NUMBER OF DOTS	640*480	
DRIVER IC	HX8250-A+HX8678-B	
INTERFACE TYPE	18-BIT RGB	
TOP POLARIZER TYPE	GLARE	
RECOMMEND VIEWING DIRECTION	6	O'CLOCK
GRAY SCALE INVERSION DIRECTION	12	O'CLOCK
BACKLIGHT TYPE	21-DIES WHITE LED	
TOUCH PANEL TYPE	WITHOUT	

2. Mechanical Drawing

MECHANICAL DRAWING DIMENSIONS:

- Overall Width: 127.00±0.2
- Overall Height: 63.92±0.8
- Panel Width: 118.16±0.2(BZ DPEN)
- Panel Height: 58.40±0.2
- Mounting Hole Spacing: 115.20(LCD A-A)
- Mounting Hole Diameter: (7.56)
- Mounting Hole Position: (6.89)
- Mounting Hole Diameter: (3.85)
- Mounting Hole Position: (86.40(LCD A-A))
- Mounting Hole Diameter: (2.55)
- Mounting Hole Position: (89.2±0.2(BZ DPENING))
- Mounting Hole Diameter: (98.43±0.2)

PIN DESCRIPTION

PIN NO	SYMBOL	DESCRIPTION
1	V/D	DATA
2	HSYNC	HORIZONTAL SYNC
3	VHSD	HORIZONTAL SYNC DATA
4	VHSD	HORIZONTAL SYNC DATA
5	VHSD	HORIZONTAL SYNC DATA
6	VHSD	HORIZONTAL SYNC DATA
7	VCC	POWER SUPPLY
8	VSYNC	VERTICAL SYNC
9	DE	DATA ENABLE
10	XL	DATA
11	YU	DATA
12	ADM	DATA
13	R5	DATA
14	B4	DATA
15	B3	DATA
16	VSS	GROUND
17	B2	DATA
18	B1	DATA
19	R0	DATA
20	VSS	GROUND
21	G5	DATA
22	G4	DATA
23	G3	DATA
24	VSS	GROUND
25	G2	DATA
26	G1	DATA
27	G0	DATA
28	VSS	GROUND
29	R5	DATA
30	R4	DATA
31	R3	DATA
32	VSS	GROUND
33	R2	DATA
34	R1	DATA
35	R0	DATA
36	XR	DATA
37	YD	DATA
38	DLK	DATA
39	VSS	GROUND
40	L/R	DATA

LED CIRCUIT DIAGRAM

LED CIRCUIT DIAGRAM: 155mA@0.6V

Pixel Detail

Pixel Detail: 0.10, 0.18

NOTES:

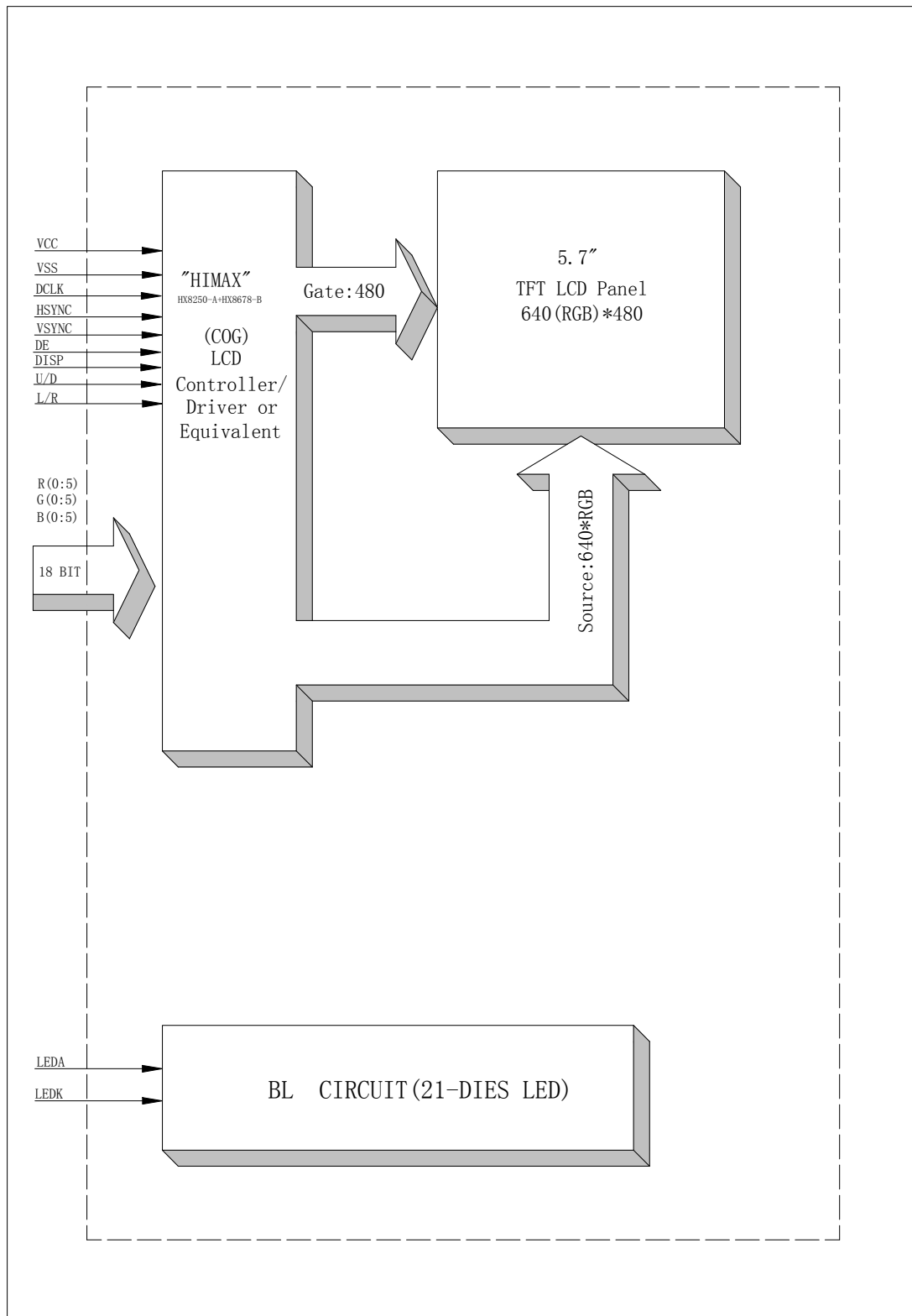
- General Tolerance: ±0.2
- () Reference dimension.
- Recommended Case Open Area Should Be Less Than Module V.A
- Recommended Panel Photo coherent area: P.V.A+1.0mm
- RGBS MUST BE COMPLIANT

Display Type	TFT, TRANSMISSIVE
Viewing Angle	NORMALLY WHITE
LCD Driver IC	HX8250-A01+HX8678B
Operating Voltage	VDD=3.3V
Operation Temperature	-20°C TO 70°C
Storage Temperature	-30°C TO 80°C
Interface	18-BIT RGB
Backlight	21-CHIP WHITE LED
Surface luminance	1000 cd/m ² (TYPE)
White X/Y	---

DRAWING NO.		TST057VGGH-02	
UNIT	mm	SCALE	1:1
FIT		SHEET 1 OF 1	

TITLE		MODULE SPEC.	
DRAWN	ME. CHECKED		
EE. CHECKED	APPROVED		
CUSTOMER'S APPROVAL	SIGN	DATE	
V00	First Issue	AMENDMENT	

3. Block Diagram



4. Interface Pin Function

Pin No.	Symbol	Description
1	U/D	Up/down scan setting. When U/D=H, reverse scan. When U/D=L, normal scan.
2	NC	No connection.
3	HSYNC	Horizontal sync input in digital RGB and CCIR601 mode. (Short to GND if not used)
4	VLED	Power supply for BLU LDO circuit.
5	VLED	Power supply for BLU LDO circuit.
6	VLED	Power supply for BLU LDO circuit.
7	VCC	Power supply.
8	VSYNC	Vertical sync input in digital RGB and CCIR601 mode. (Short to GND if not used)
9	DE	Input data enable control. When DE mode, active High to enable data input. Default pull low.
10	NC(X2)	No connection.(Touch panel control PIN: X2)
11	NC(Y1)	No connection.(Touch panel control PIN: Y1)
12	ADJ	Chip Enable (Active High).
13	B5	Blue data input.
14	B4	Blue data input
15	B3	Blue data input
16	VSS	Power ground.
17	B2	Blue data input.
18	B1	Blue data input.
19	B0	Blue data input.
20	VSS	Power ground.
21	G5	Green data input.
22	G4	Green data input.
23	G3	Green data input.
24	VSS	Power ground.
25	G2	Green data input.
26	G1	Green data input.
27	G0	Green data input.
28	VSS	Power ground.
29	R5	Red data input.
30	R4	Red data input.
31	R3	Red data input.
32	VSS	Power ground.
33	R2	Red data input.
34	R1	Red data input.
35	R0	Red data input.
36	NC(X1)	No connection.(Touch panel control PIN: X1)
37	NC(Y2)	No connection.(Touch panel control PIN: Y2)

38	DCLK	Clock signal. Latching data at the rising edge.
39	VSS	Power ground.
40	L/R	The shift direction of device internal shift register is controlled by this pin as shown below: L/R=H: STH->SO1->•••->SO960->STHO L/R=L: STH->SO960->•••->SO1->STHO

5. Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit
Supply voltage for analog	VCC	-0.5	5.0	V
Supply voltage for logic	VCC	-0.5	5.0	V
Supply current (One LED)	I _{LED}		40	mA
Operating temperature	T _{OP}	-20	+70	°C
Storage temperature	T _{ST}	-30	+80	°C

Note : The absolute maximum rating values of this product are not allowed to be exceeded at any times. Should a module be used with any of the absolute maximum ratings exceeded, the characteristics of the module may not be recovered, or in an extreme case, the module may be permanently destroyed.

6. Electrical Characteristics

6.1 Input Power

Item	Symbol	Min	Typ.	Max	Unit	Applicable terminal
Supply Voltage for Analog	VCC	2.7	3.3	3.6	V	
Supply Voltage for Logic	VCC	2.7	3.3	3.6	V	
Input Voltage	V _{IL}	-0.3	-	0.2VCC	V	
	V _{IH}	0.8 VCC	-	VCC		
Input leakage Current	I _{LKG}	-1		1	μA	

6.2 Backlight Driving Conditions

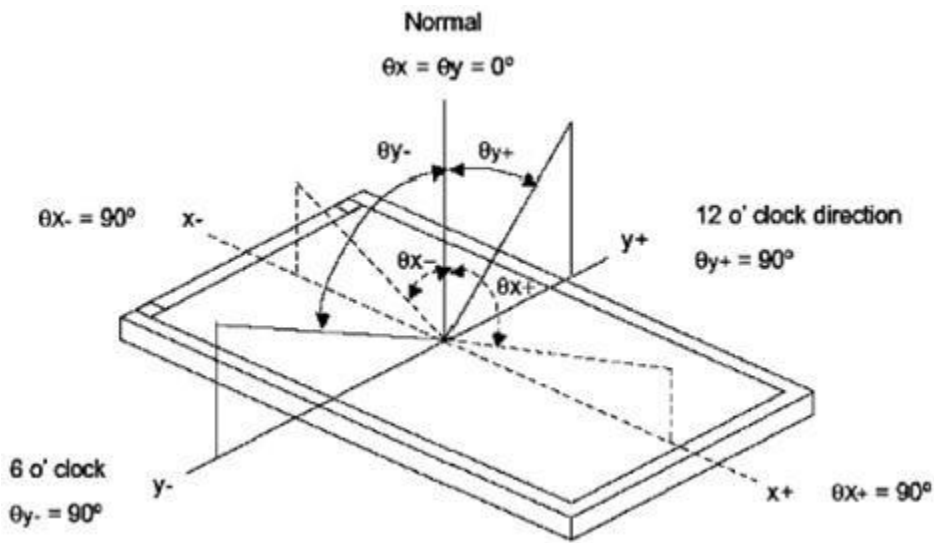
Item	Symbol	Value			Unit	Remark
		Min.	Typ.	Max.		
Voltage for LED Backlight	V _F	8.4	9.6	10.2	V	I _L =155mA
Current for LED Backlight	I _L		155		mA	
Power Consumption	P		1.488		W	
LED Life Time		30,000	50,000		Hr	Note
Power supply for LED	V _{LED}	4.5	5.0	5.5	V	
ADJ frequency		19K	20K	21K	Hz	
ADJ input voltage	V _{IH}	3.0		3.3	V	
ADJ input voltage	V _{IL}	0		0.3	V	

Note: Brightness to be decreased to 50% of the initial value at ambient temperature TA=25°C

7. Optical Characteristics

ITEM	SYMBOL	CONDITIONS	SPECIFICATIONS			UNIT	NOTE
			MIN	TYP.	MAX		
Luminance	L	$I_L = 155\text{mA}$	800	1000	1200	Cd/m^2	
Contrast Ratio	CR	$\theta = 0^\circ$		450			
Response Time	T_{ON}	25°C		TBD		ms	
	T_{OFF}						
CIE Color Coordinate	Red	X_R	Viewing normal angle	0.587	0.607	0.627	
		Y_R		0.344	0.364	0.384	
	Green	X_G		0.329	0.349	0.369	
		Y_G		0.543	0.563	0.583	
	Blue	X_B		0.122	0.142	0.162	
		Y_B		0.117	0.137	0.157	
	White	X_W		0.268	0.288	0.2308	
		Y_W		0.301	0.321	0.341	
Viewing Angle	Hor.	θ_{x+}	$\text{CR} \geq 10$		70		Degree
		θ_{x-}			70		
	Ver.	θ_{y+}			60		
		θ_{y-}			40		
Uniformity	Un		75	80		%	

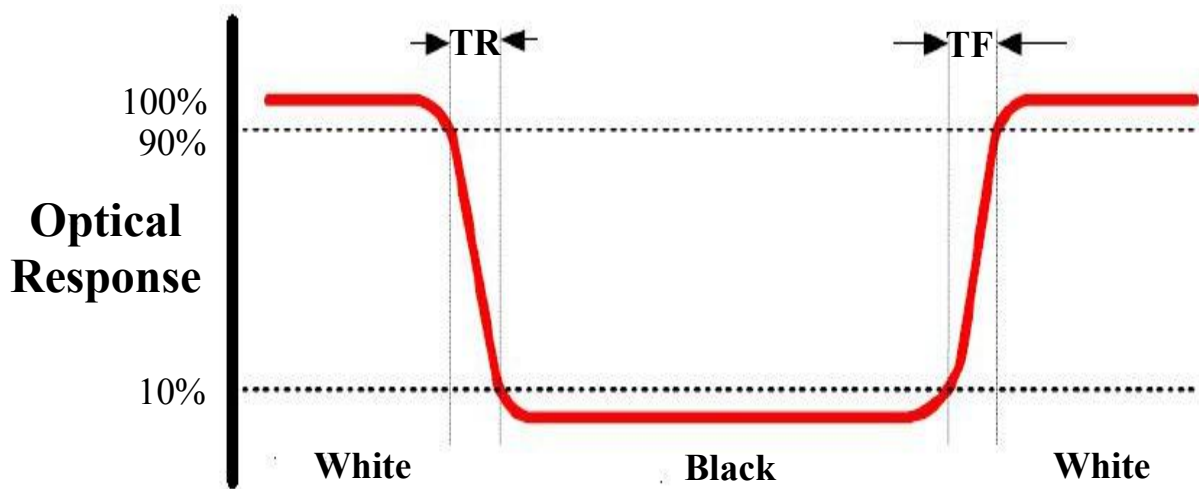
Note 1: Definition of Viewing Angle θ_x and θ_y :



Note 2: Definition of contrast ratio CR:

$$CR = \frac{\text{Luminance of white state}}{\text{Luminance of black state}}$$

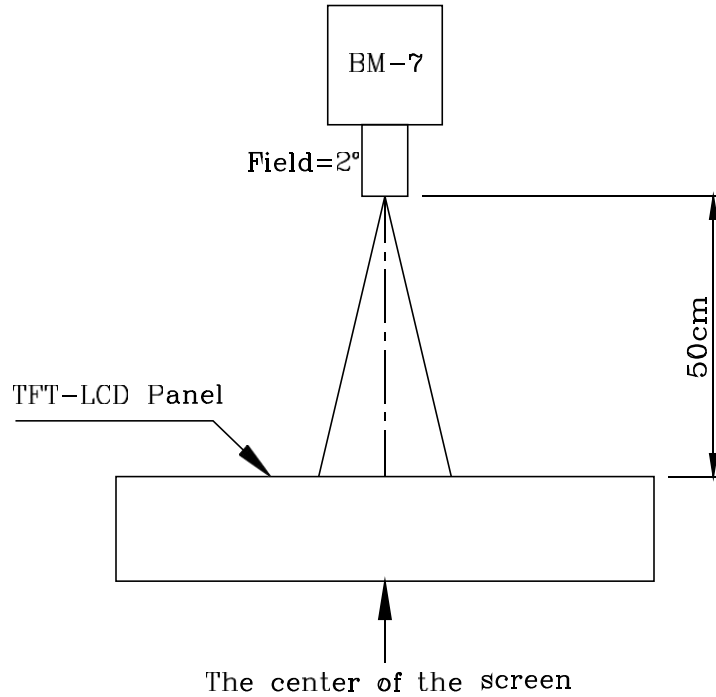
Note 3: Definition of Response Time(T_r, T_f)



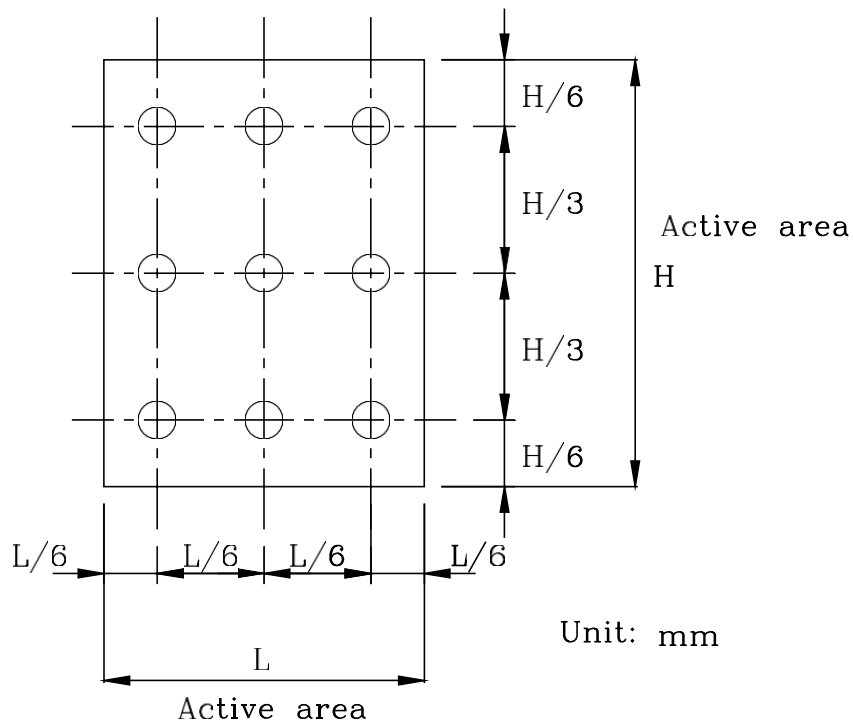
Note 4: Definition of Luminance

① The Brightness Test Equipment Setup

Field=2° (As measuring “black” image, field=2° is the best testing condition)



② The Brightness Test Point Setup



8. Timing Characteristics

8.1 AC Electrical Characteristics

PARAMETER	Symbol	Spec.			Unit
		Min.	Typ.	Max.	
HS setup time	T_{hst}	10	-	-	ns
HS hold time	T_{hhd}	10	-	-	ns
VS setup time	T_{vst}	10	-	-	ns
VS hold time	T_{vhd}	10	-	-	ns
Data setup time	T_{dsu}	10	-	-	ns
Data hold time	T_{dhd}	10	-	-	ns
DEN setup time	T_{esu}	10	-	-	ns
VS falling to HS falling time on odd field @ RGB mode	T_{HV_O}	-4	0	+4	T_{CPH}
VS falling to HS falling time on even field @ RGB mode	T_{HV_E}	0.4	0.5	0.6	T_H
Source output settling time	T_{ST}	-	12	20	μs
Source output loading R	R_{SL}	-	2	-	K ohm
Source output loading C	C_{SL}	-	60	-	pF
POL output delay time	T_{DP}	-	-	40	ns

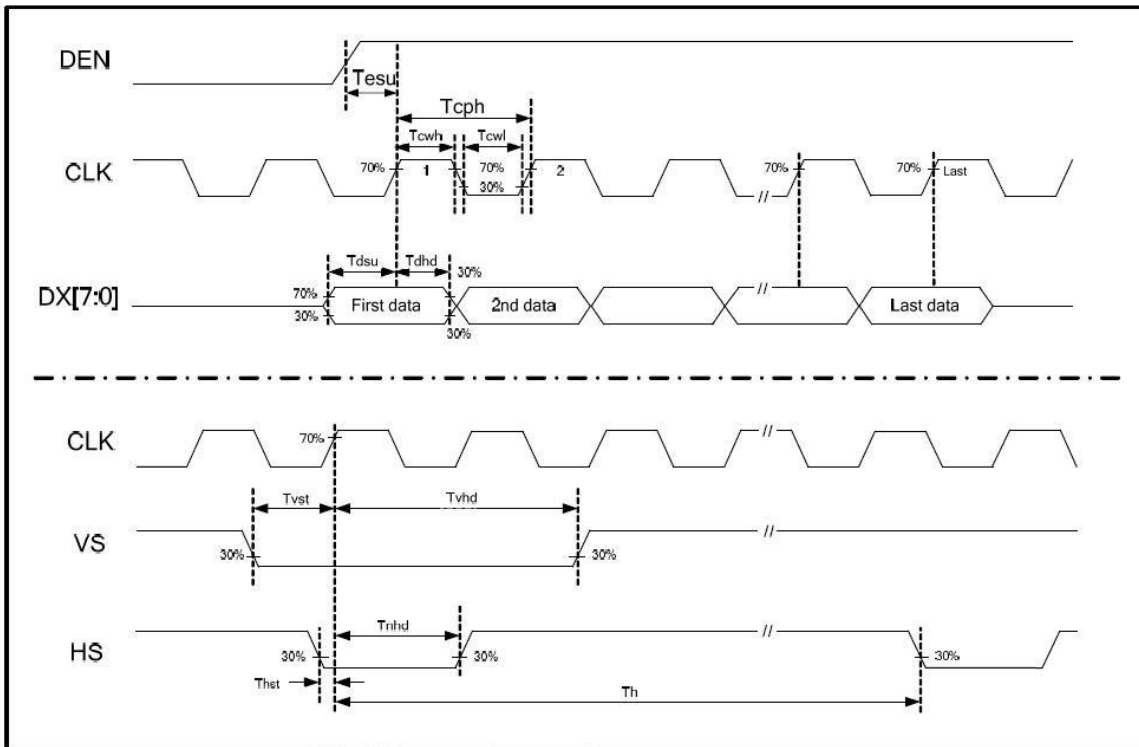
8.2 Digital Parallel RGB interface

PARAMETER	Symbol	Spec.			Unit
		Min.	Typ.	Max.	
CLK frequency	F_{CPH}	-	25.175	-	MHz
CLK period	T_{CPH}	-	39.7	-	ns
CLK pulse duty	T_{CWH}	40	50	60	%
HS period	T_H	-	800	-	T_{CPH}
HS pulse width	T_{WH}	5	30	-	T_{CPH}
HS-first horizontal data time	T_{HS}	112	144	175	T_{CPH}
DEN pulse width	T_{EP}	-	640	-	T_{CPH}
VS pulse width	T_{WV}	1	3	5	T_H
VS-DEN time	T_{STV}	-	35	-	T_H
VS period	T_V	-	525	-	T_H

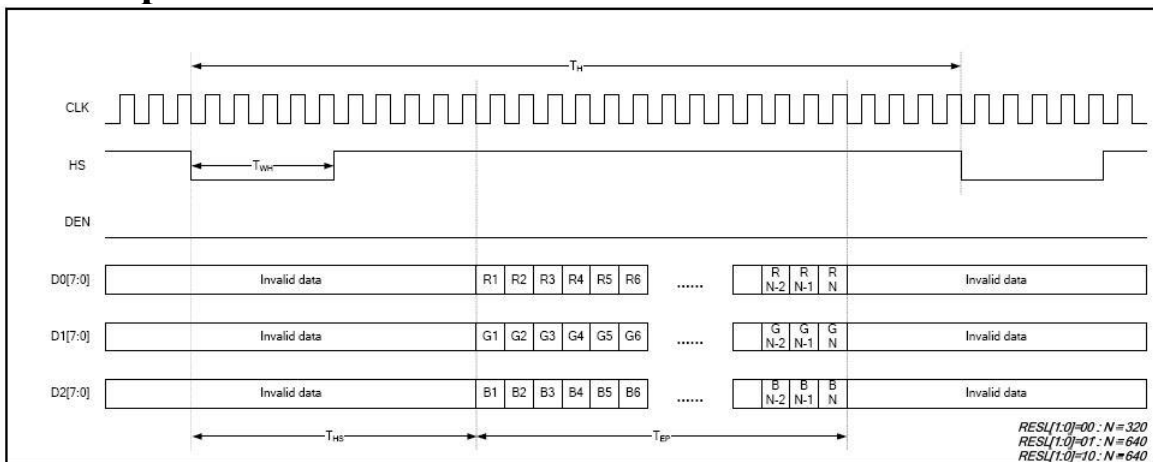
Note: When SYNC mode is used, 1st data start from 144th CLK after HS falling (when $STHD[5:0]=00000$)

PARAMETER	Symbol	Spec.			Unit
		Min.	Typ.	Max.	
OEV pulse width	T_{OEV}	-	100	-	T_{CPH}
CKV pulse width	T_{CKV}	-	96	-	T_{CPH}
HS-CKV time	T_1	-	52	-	T_{CPH}
HS-OEV time	T_2	-	8	-	T_{CPH}
HS-POL time	T_3	-	72	-	T_{CPH}
STV setup time	T_{SUV}	-	46	-	T_{CPH}
STV pulse width	T_{WSTV}	-	1	-	T_H

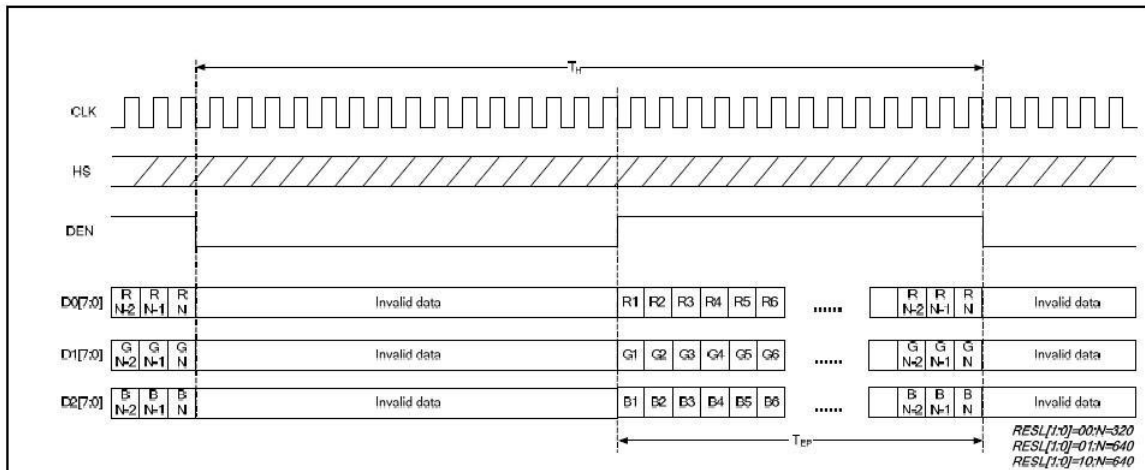
8.3 Clock and Data input waveforms



8.4 Data input format for RGB mode



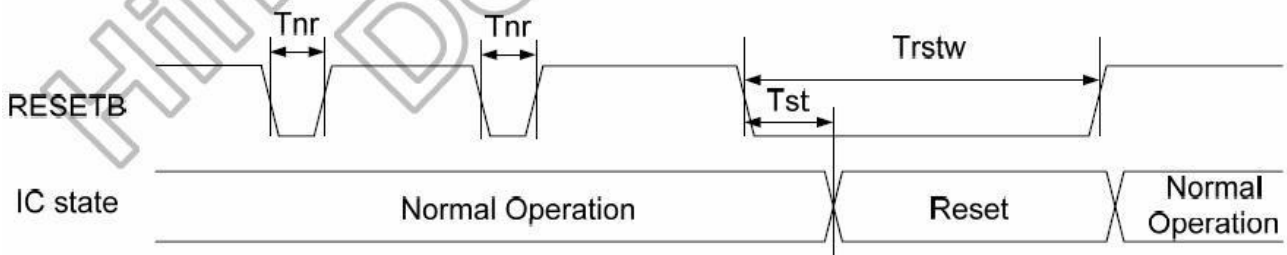
Parallel RGB SYNC Mode Horizontal Data Format



Parallel RGB DE Mode Horizontal Data Format

8.5 Hardware reset timing

PARAMETER	Symbol	Spec.			Unit
		Min.	Typ.	Max.	
RESETB low pulse width	T_{rstw}	10	-	-	μs
Negative noise pulse width	T_{nr}		-	2	μs
Reset start time	T_{st}	2	-		μs



9. Standard Specification for Reliability

9.1 Standard Specification for Reliability of LCD Module

No	Test Item	Condition	Remarks
1	High Temperature Operation	Ts = +70°C, 240 hours	IEC60068-2-1:2007 GB2423.2-2008
2	Low Temperature Operation	Ta = -20°C, 240 hours	IEC60068-2-1:2007 GB2423.1-2008
3	High Temperature Storage	Ta = +80°C, 240 hours	IEC60068-2-1:2007 GB2423.2-2008
4	Low Temperature Storage	Ta = -30°C, 240 hours	IEC60068-2-1:2007 GB2423.1-2008
5	Storage at High Temperature and Humidity	Ta = +60°C, 90% RH max,240hours	IEC60068-2-78 :2001 GB/T2423.3—2006
6	Thermal Shock (non-operation)	-30°C 30 min~+80°C 30 min, Change time:5min, 20 Cycle	Start with cold temperature, End with high temperature, IEC60068-2-14:1984,G B2423.22-2002
7	ESD	C=150pF,R=330Ω,5point/panel Air:±8Kv,5times; Contact:±4Kv,5times (Environment:15°C~35°C, 30%~60%.86Kpa~106Kpa)	IEC61000-4-2:2001 GB/T17626.2-2006
8	Vibration Test	Frequency range:10~55Hz Stroke:1.5mm Sweep:10Hz~55Hz~10Hz 2 hours for each direction of X.Y.Z. (6 hours for total)	IEC60068-2-6:1982 GB/T2423.10—1995
9	Mechanical Shock (Non Op)	Half Sine Wave 60G 6ms, ±X,±Y,±Z 3times for each direction	IEC60068-2-27:1987 GB/T2423.5—1995
10	Package Drop Test	Height:80cm, 1corner,3 edges,6 surfaces	IEC60068-2-32:1990 GB/T2423.8—1995

Note1: Ts is the temperature of panel's surface.

Note2: Ta is the ambient temperature of samples.

9.2 Testing Conditions and Inspection Criteria

For the final test, the testing sample must be stored at room temperature for 24 hours. After the tests listed in Table 9.2, standard specifications for reliability will be executed in order to ensure stability.

No.	Item	Test Model	In section Criteria
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
03	Appearance	Visual inspection	Defect free.

9.3 MTBF

MTBF	<p>Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature (25±5°C), normal humidity (50±10% RH),and in area not exposed to direct sun light.</p>
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10. Specification of Quality Assurance

This standard of Quality Assurance confirms to the quality of LCD module products supplied by Tecenstar.

10.1 Quality Test

Before delivering, the supplier should conduct the following tests to confirm the quality of products.

- Electrical-Optical Characteristics: According to the individual specification to test the product.
- Appearance Characteristics: According to the individual specification to test the product.
- Reliability Characteristics: According to the definition of reliability on the specification for testing products.

10.2 Delivery Test

Before delivering, the supplier should conduct the delivery test.

- Test method: According to MIL-STD105E.General Inspection Level II take a single Time.
- The defects classify of AQL as following:
Major defect: AQL = 0.65
Minor defect: AQL = 1.5
Total defects: AQL = 1.5

10.3 Non-conforming Analysis & Deal With Manners

10.3.1 Non-conforming Analysis

- Purchaser should provide the data detail of non-conforming sample and the non-conforming.
- After receiving the data detail from purchaser, the analysis of non-conforming should be finished within two weeks.
- If the analysis can't be finished on time, supplier must notice purchaser 3 days in advance.

10.3.2 Disposition of non-conforming

- If any product defect be found during assembling, supplier must change the good for every defect after confirmation.
- Both supplier and customer should analyze the reason and discuss the disposition of non-conforming when the reason of nonconforming is not sure.

10.4 Agreement items

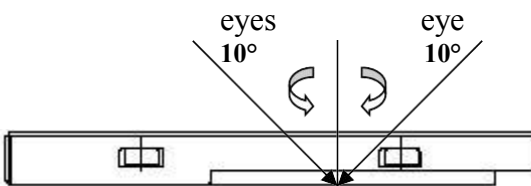
Both parties should negotiate together when the following problems happen.

- There is any problem of standard of quality assurance, and both sides should agree that it must be modified.
- There is any argument item which does not record in the standard of quality assurance.
- Any other special problem.

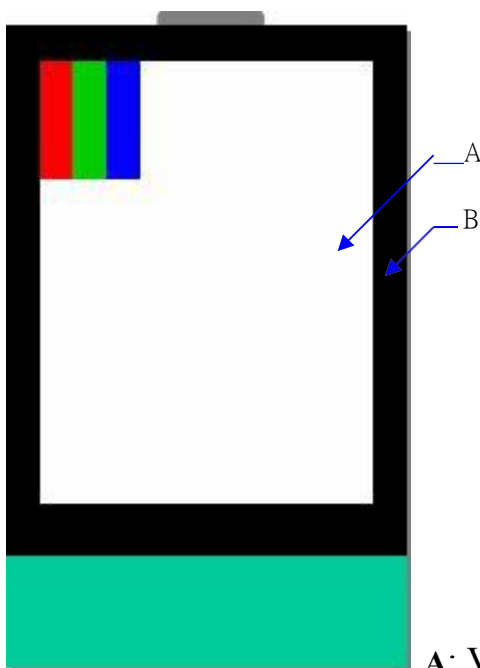
10.5 Standard of The Product Appearance Test

10.5.1 Manner of appearance test

- The test must be under 20W × 2 or 40W fluorescent light, and the distance of view must be at 30±5cm.
- When test the model of transmissive product must add the reflective plate.
- The test direction is base on around 10° of vertical line.
- Temperature: 25±5°C Humidity: 60±10%RH



- Definition of area:

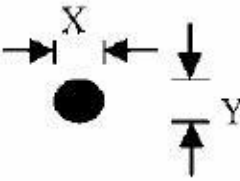
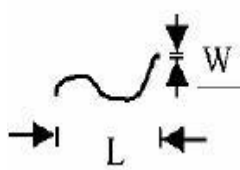


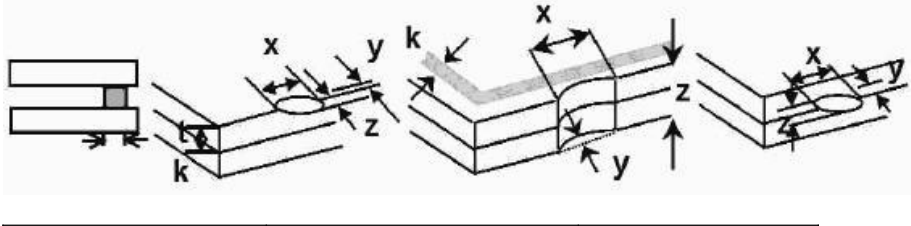
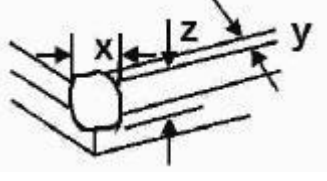
A: Viewing area B: Outside viewing area

10.5.2 Basic principle

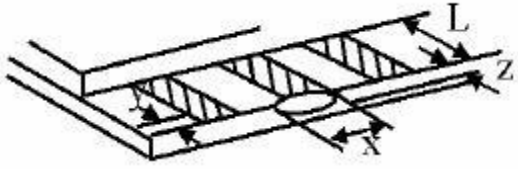
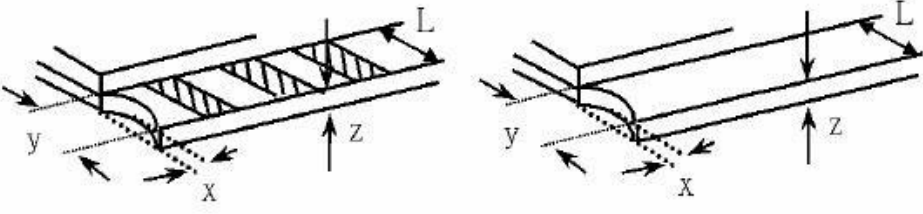
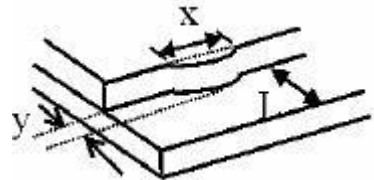
- When the standard can not be described, AQL will be applied.
- The sample of the lowest acceptable quality level must be negotiated by both supplier and customer when any dispute happened.
- New item must be added on time when it is necessary.

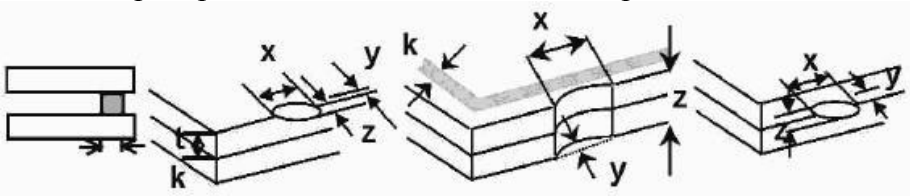
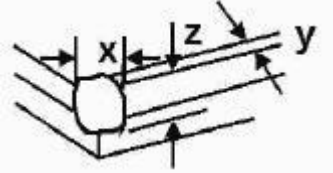
10.6 Inspection Specification

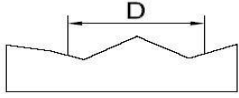
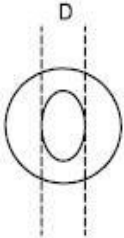
NO.	Item	Criterion	AQL												
01	Electrical Testing	1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Flicker	0.65												
02	Black or White spots or Bright spots or Color spots on LCD (Display only)	21 White and black or color spots on display $\leq 0.25\text{mm}$, no more than Five spots. 22 Densely spaced: No more than three spots within 3mm.	1.5												
03	LCD and Touch Panel black spots, white spots, contamination (non – display)	3.1 Round type: As following drawing $\Phi = (X+Y) / 2$  <table border="1" data-bbox="821 1131 1348 1377"> <thead> <tr> <th>Size(mm)</th> <th>Acceptable Q'ty</th> </tr> </thead> <tbody> <tr> <td>$\Phi \leq 0.10$</td> <td>Accept no dense</td> </tr> <tr> <td>$0.10 < \Phi \leq 0.20$</td> <td>2</td> </tr> <tr> <td>$0.20 < \Phi \leq 0.25$</td> <td>2</td> </tr> <tr> <td>$0.25 < \Phi \leq 0.30$</td> <td>1</td> </tr> <tr> <td>$0.30 < \Phi$</td> <td>0</td> </tr> </tbody> </table> <p>* Densely spaced: No more than two spots within 3mm.</p>	Size(mm)	Acceptable Q'ty	$\Phi \leq 0.10$	Accept no dense	$0.10 < \Phi \leq 0.20$	2	$0.20 < \Phi \leq 0.25$	2	$0.25 < \Phi \leq 0.30$	1	$0.30 < \Phi$	0	1.5
		Size(mm)	Acceptable Q'ty												
$\Phi \leq 0.10$	Accept no dense														
$0.10 < \Phi \leq 0.20$	2														
$0.20 < \Phi \leq 0.25$	2														
$0.25 < \Phi \leq 0.30$	1														
$0.30 < \Phi$	0														
3.2 Line type: (As following drawing)  <table border="1" data-bbox="726 1534 1348 1803"> <thead> <tr> <th>Length(mm)</th> <th>Width(mm)</th> <th>Acceptable Q'ty</th> </tr> </thead> <tbody> <tr> <td>---</td> <td>$W \leq 0.02$</td> <td>Accept no dense</td> </tr> <tr> <td>$L \leq 3.0$</td> <td>$0.02 < W \leq 0.05$</td> <td rowspan="2">2</td> </tr> <tr> <td>$L \leq 2.5$</td> <td>$0.03 < W \leq 0.08$</td> </tr> <tr> <td>---</td> <td>$0.08 < W$</td> <td>Rejection</td> </tr> </tbody> </table> <p>* Densely spaced: No more than two lines within 3mm.</p>	Length(mm)	Width(mm)	Acceptable Q'ty	---	$W \leq 0.02$	Accept no dense	$L \leq 3.0$	$0.02 < W \leq 0.05$	2	$L \leq 2.5$	$0.03 < W \leq 0.08$	---	$0.08 < W$	Rejection	1.5
Length(mm)	Width(mm)	Acceptable Q'ty													
---	$W \leq 0.02$	Accept no dense													
$L \leq 3.0$	$0.02 < W \leq 0.05$	2													
$L \leq 2.5$	$0.03 < W \leq 0.08$														
---	$0.08 < W$	Rejection													

NO.	Item	Criterion			AQL	
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction	Size Φ (mm)	Acceptable Q'ty	1.5	
			$\Phi \leq 0.20$	Accept no dense		
			$0.20 < \Phi \leq 0.50$	3		
			$0.50 < \Phi \leq 1.00$	2		
			$1.00 < \Phi$	0		
			Total Q'ty	3		
05	Scratches	Follow NO.3 -2 Line Type.				
06	Chipped glass	<p>Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 6.1 General glass chip: 6.1.1 Chip on panel surface and crack between panels:</p> 	z: Chip thickness	y: Chip width	x: Chip length	1.5
			$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$	
			$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$	
			⊙ Unit: mm			
			⊙ If there are 2 or more chips, x is the total length of each chip			
			6.1.2 Corner crack:			
	z: Chip thickness	y: Chip width	x: Chip length			
$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$				
$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$				
⊙ Unit: mm						
⊙ If there are 2 or more chips, x is the total length of each chip						

NO.	Item	Criterion	AQL
08	Cracked glass	The LCD with extensive crack is not acceptable.	1.5
09	Backlight elements	9.1 Illumination source flickers when lit. 9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 9.3 Backlight doesn't light or color is wrong.	1.5 1.5 0.65
10	Bezel	Bezel must comply with product specifications.	1.5
11	PCB、COB	11.1 COB seal may not have pinholes larger than 0.2mm or contamination. 11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram. 11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 11.6 The jumper on the PCB should conform to the product characteristic chart.	1.5 1.5 1.5 1.5 0.65 0.65
12	FPC	12.1 FPC terminal damage \cong 1/2 FPC terminal width and can not affect the function , we judge accept. 12.2 FPC alignment hole damage \cong 1/2 alignment area and can not affect the function , we judge accept.	1.5 1.5
13	Soldering	13.1 No cold solder joints, missing solder connections, oxidation or icicle. 13.2 No short circuits in components on PCB or FPC.	1.5 0.65

NO.	Item	Criterion	AQL																
07	Glass crack	<p>Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length</p> <p>7.2 Protrusion over terminal: 7.2.1 Chip on electrode pad:</p>  <table border="1" data-bbox="558 761 1236 907"> <tr> <td>y: Chip width</td> <td>x: Chip length</td> <td>z: Chip thickness</td> </tr> <tr> <td>$y \leq 0.5\text{mm}$</td> <td>$x \leq 1/8a$</td> <td>$0 < z \leq t$</td> </tr> </table> <p>7.2.2 Non-conductive portion:</p>  <table border="1" data-bbox="558 1276 1236 1422"> <tr> <td>y: Chip width</td> <td>x: Chip length</td> <td>z: Chip thickness</td> </tr> <tr> <td>$y \leq L$</td> <td>$x \leq 1/8a$</td> <td>$0 < z \leq t$</td> </tr> </table> <p>⊙ If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. ⊙ If the product will be heat sealed by the customer, the alignment mark must not be damaged.</p> <p>7.2.3 Substrate protuberance and internal crack</p>  <table border="1" data-bbox="885 1747 1324 1892"> <tr> <td>y: width</td> <td>x: length</td> </tr> <tr> <td>$y \leq 1/3L$</td> <td>$X \leq a$</td> </tr> </table>	y: Chip width	x: Chip length	z: Chip thickness	$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$	y: Chip width	x: Chip length	z: Chip thickness	$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$	y: width	x: length	$y \leq 1/3L$	$X \leq a$	1.5
y: Chip width	x: Chip length	z: Chip thickness																	
$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$																	
y: Chip width	x: Chip length	z: Chip thickness																	
$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$																	
y: width	x: length																		
$y \leq 1/3L$	$X \leq a$																		

NO.	Item	Criterion	AQL												
14	Touch Panel Chipped glass	<p>Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Touch Panel Total thickness a: LCD side length L: Electrode pad length</p> <p>14.1 General glass chip: 14.1.1 Chip on panel surface and crack between panels:</p>  <table border="1" data-bbox="453 763 1270 981"> <tr> <td>z: Chip thickness</td> <td>y: Chip width</td> <td>x: Chip length</td> </tr> <tr> <td>$Z \leq t$</td> <td>$\cong 1/2 k$ and not over viewing area</td> <td>$x \leq 1/8a$</td> </tr> </table> <p>⊙ Unit: mm ⊙ If there are 2 or more chips, x is the total length of each chip</p> <p>14.1.2 Corner crack:</p>  <table border="1" data-bbox="453 1361 1270 1579"> <tr> <td>z: Chip thickness</td> <td>y: Chip width</td> <td>x: Chip length</td> </tr> <tr> <td>$z \leq t$</td> <td>$\cong 1/2 k$ and not over viewing area</td> <td>$x \leq 1/8a$</td> </tr> </table> <p>⊙ Unit: mm ⊙ If there are 2 or more chips, x is the total length of each chip</p>	z: Chip thickness	y: Chip width	x: Chip length	$Z \leq t$	$\cong 1/2 k$ and not over viewing area	$x \leq 1/8a$	z: Chip thickness	y: Chip width	x: Chip length	$z \leq t$	$\cong 1/2 k$ and not over viewing area	$x \leq 1/8a$	1.5
z: Chip thickness	y: Chip width	x: Chip length													
$Z \leq t$	$\cong 1/2 k$ and not over viewing area	$x \leq 1/8a$													
z: Chip thickness	y: Chip width	x: Chip length													
$z \leq t$	$\cong 1/2 k$ and not over viewing area	$x \leq 1/8a$													

NO.	Item	Criterion	AQL										
15	Touch Panel(Fish eye、dent and bubble on film)	<table border="1"> <thead> <tr> <th>SIZE(mm)</th> <th>Acceptable Q'ty</th> </tr> </thead> <tbody> <tr> <td>$\Phi \leq 0.2$</td> <td>Accept no dense</td> </tr> <tr> <td>$0.2 < D \leq 0.4$</td> <td>5</td> </tr> <tr> <td>$0.4 < D \leq 0.5$</td> <td>2</td> </tr> <tr> <td>$0.5 < D$</td> <td>0</td> </tr> </tbody> </table>  	SIZE(mm)	Acceptable Q'ty	$\Phi \leq 0.2$	Accept no dense	$0.2 < D \leq 0.4$	5	$0.4 < D \leq 0.5$	2	$0.5 < D$	0	1.5
SIZE(mm)	Acceptable Q'ty												
$\Phi \leq 0.2$	Accept no dense												
$0.2 < D \leq 0.4$	5												
$0.4 < D \leq 0.5$	2												
$0.5 < D$	0												
16	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion($\leq 2.5\%$) , it is acceptable.	1.5										
17	Touch Panel Linearity	Less than 2.5% is acceptable.	1.5										
18	LCD Ripple	Touch the touch panel , can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g	1.5										
19	General appearance	19.1 Pin type must match type in specification sheet. 19.2 LCD pin loose or missing pins. 19.3 Product packaging must the same as specified on packaging specification sheet. 19.4 Product dimension and structure must conform to product specification sheet.	0.65 0.65 0.65 0.65										

11. Handling Precaution

11.1 Handling of LCM

- Avoid external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance, do not lick or swallow. When the liquid is attaching to your hand, skin, cloth, etc., wash it thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should wear protections whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface, be careful when peeling off this protective film since static electricity may be generated.

11.2 Storage

- Store it in an ambient temperature of $25\pm 10^{\circ}\text{C}$, and in a relative humidity of $50\pm 10\%\text{RH}$. Don't expose to sunlight or fluorescent light.
- Store it in a clean environment, free from dust, active gas, and solvent.
- Store it in anti-static electricity container.
- Store it without any physical load.

11.3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: no higher than $280\pm 10^{\circ}\text{C}$ and less than 3 sec during hand soldering.
- Rewiring: no more than 2 times.

12. Packing Method

TBD